

Edition Ltd.
(Incorporated in Singapore)
(Company Registration No. 200411873E)

UPDATE ON THE TENURE OF THE AGGREGATE LOAN PRINCIPAL OF S\$1,687,500 EXTENDED BY EDITION LTD. TO HYPERLYNC TECHNOLOGIES LIMITED

1. INTRODUCTION

The Board of Directors (the “**Board**”) of Edition Ltd. (the “**Company**”, together with its subsidiaries, the “**Group**”) refers to its announcements on:

- (a) 5 June 2018 in relation to the Binding Memorandum of Understanding (“**MOU**”) entered by the Company with Hyperlync Technologies Limited (“**Hyperlync**”) to acquire a 51% stake in the enlarged share capital of Hyperlync;
- (b) 13 August 2018 in relation to the entering of the Supplemental Loan Agreement to amend the Loan Agreement entered into with Hyperlync; and
- (c) 12 December 2018 in relation to the termination of the MOU and entering of the Second Supplemental Loan Agreement to further amend the Loan Agreement (“**12 December 2018 Announcement**”)

(Collectively, the “**Announcements**”).

Unless otherwise defined herein, all capitalised terms and references used herein shall bear the same meaning ascribed to them in the Announcements.

2. UPDATE ON THE TENURE OF THE LOAN

With reference to paragraph 3(a) of the 12 December 2018 Announcement on the agreed tenure of the aggregate loan principal of S\$1,687,500 that was extended from 6 December 2018 to 11 June 2019, the Board wishes to inform that the Company is in discussion with Hyperlync to further extend the tenure of the loan and will update shareholders when both parties have agreed on the terms.

3. CAUTIONARY STATEMENT

Shareholders and potential investors should exercise caution when trading in the Company’s shares, as there is no certainty that completion will take place. In the event of any doubt as to the action they should take, shareholders and potential investors should consult their financial, tax, legal or other professional advisors.

By Order of the Board
Edition Ltd.

Ong Boon Chuan
Executive Chairman and Chief Executive Officer
11 June 2019

This announcement has been reviewed by the Company's Sponsor, SAC Capital Private Limited (the "Sponsor"). It has not been examined or approved by the Singapore Exchange Securities Trading Limited (the "Exchange") and the Exchange assumes no responsibility for the contents of this announcement, including the correctness of any of the statements or opinions made or reports contained in this announcement.

The contact person for the Sponsor is Ms Tay Sim Yee (Telephone no.: (65) 6232 3210) at 1 Robinson Road, #21-00 AIA Tower, Singapore 048542.